

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATIONS

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: Semiconductor Element-Mounting Board, Manufacturing Method
For the Board, Semiconductor Device and Manufacturing Method
For the Device

of which is described and claimed in:

() the attached specification, or

(X) the specification in the application Serial No. _____ filed July 8, 1997;
 and with amendments through _____ (if applicable),

() the specification in International Application No. PCT/ _____, filed
 _____, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose information of which I am aware which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	8-179031	July 9, 1996	(X) YES () NO
_____	_____	_____	() YES () NO
_____	_____	_____	() YES () NO
_____	_____	_____	() YES () NO
_____	_____	_____	() YES () NO
_____	_____	_____	() YES () NO

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

SERIAL NO.	U.S. FILING DATE	STATUS
_____	_____	() Patented () Pending () Abandoned
_____	_____	() Patented () Pending () Abandoned
_____	_____	() Patented () Pending () Abandoned

And I hereby appoint John T. Miller, Reg. No. 21,120; Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Jeffrey Nolton, Reg. No. 25,408; Warren M. Cheek, Jr., Reg. No. 33,367; Nils E. Pedersen, Reg. No. 33,145; and Charles R. Watts, Reg. 33,142; who together constitute the firm of WENDEROTH, LIND & PONACK, jointly and severally, attorneys to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys named herein to accept and follow instructions from Aoyama & Partners as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Send Correspondence to

Direct Telephone Calls to:

WENDEROTH, LIND & PONACK

WENDEROTH, LIND & PONACK

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the Rule of the United States Patent Office for recordation of this document.

FULL NAME OF 1ST INVENTOR	FAMILY NAME HIGASHIDA	FIRST GIVEN NAME Takaaki	SECOND GIVEN NAME
RESIDENCE & CITIZENSHIP	CITY Kadoma-shi, Osaka-fu, Japan	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP Japan
POST OFFICE ADDRESS	ADDRESS 25-2, Oike-cho, Kadoma-shi, Osaka-fu, 571 Japan	CITY	STATE OR COUNTRY Japan ZIP CODE
FULL NAME OF 2ND INVENTOR	FAMILY NAME KUMAGAI	FIRST GIVEN NAME Koichi	SECOND GIVEN NAME
RESIDENCE & CITIZENSHIP	CITY Ikoma-shi, Nara-ken, Japan	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP Japan
POST OFFICE ADDRESS	ADDRESS 2-10-16, Hikarigaoka, Ikoma-shi, Nara-ken, 630-01	CITY	STATE OR COUNTRY Japan ZIP CODE
FULL NAME OF 3RD INVENTOR	FAMILY NAME MATSUO	FIRST GIVEN NAME Takahiro	SECOND GIVEN NAME
RESIDENCE & CITIZENSHIP	CITY Hirakata-shi, Osaka-fu, Japan	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP Japan
POST OFFICE ADDRESS	ADDRESS 3-18, Chugu-higashino-cho, Hirakata-shi, Osaka-fu,	CITY	STATE OR COUNTRY 573 Japan ZIP CODE
FULL NAME OF 4TH INVENTOR	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
RESIDENCE & CITIZENSHIP	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
POST OFFICE ADDRESS	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
FULL NAME OF 5TH INVENTOR	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
RESIDENCE & CITIZENSHIP	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
POST OFFICE ADDRESS	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
FULL NAME OF 6TH INVENTOR	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
RESIDENCE & CITIZENSHIP	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
POST OFFICE ADDRESS	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor Takaaki Higashida Date August 1, 1997
 2nd Inventor Koichi Kumagai Date August 1, 1997
 3rd Inventor Takahiro Matsuo Date August 1, 1997
 4th Inventor _____ Date _____
 5th Inventor _____ Date _____
 6th Inventor _____ Date _____

The above application may be more particularly identified as follows:

U. S. Application Serial No. 08/890,009....., Filing Date July 8, 1997.....

Applicant Reference Number 526161....., Atty Docket No. 177/526161.....

Title of Invention Semiconductor Element-Mounting Board, Manufacturing Method For the Board, Semiconductor Device and Manufacturing Method For the Device